

**N-Ch MOSFET** 

### **General Description**

The WST6002 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST6002 meet the RoHS and Green Product requirement with full function reliability approved.

#### Features

- High-speed switching
- Green Device Available
- ESD Protected:2KV

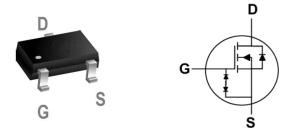
## **Product Summery**

BVDSS	RDSON	ID
30V	5Ω	100mA

## Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC
- Networking DC-DC Power System
- Load Switch

#### SOT-523 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V <sub>DS</sub>	Drain-Source Voltage	30	V	
V <sub>GS</sub>	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	mA		
I <sub>D</sub> @T <sub>A</sub> =70℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	60	mA	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup> 0.5		А	
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>3</sup>	0.15	W	
T <sub>STG</sub>	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	

## **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		625	°C/W



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## Electrical Characteristics (T<sub>J</sub>=25 $\odot$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V , $I_{D}$ =250uA	30			V
$\triangle BV_{DSS} / \triangle T_J$	BV <sub>DSS</sub> Temperature Coefficient	Reference to $25^\circ\!\!\mathbb{C}$ , I_D=1mA		0.05		V/℃
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =0.01A			5	Ω
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =0.01A			13	
V <sub>GS(th)</sub>	Gate Threshold Voltage		1		2.5	V
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient			-3.7		mV/℃
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =24V , $V_{GS}$ =0V , $T_J$ =25 $^\circ\!\mathrm{C}$			1	
		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	- uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±10	uA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =0.1A		450		mS
T <sub>d(on)</sub>	Turn-On Delay Time			2	3.5	
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V ,		1.0	2.2	ns
T <sub>d(off)</sub>	Turn-Off Delay Time	R <sub>G</sub> =3.3Ω, I <sub>D</sub> =0.1A		5	9	
T <sub>f</sub>	Fall Time			1.5	2.5	
C <sub>iss</sub>	Input Capacitance			9		
C <sub>oss</sub>	Output Capacitance	$V_{DS}$ =15V , $V_{GS}$ =0V , f=1MHz		5		pF
Crss	Reverse Transfer Capacitance			2		

## **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,4</sup>	$V_G = V_D = 0V$ , Force Current			100	mA
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>				0.5	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	$V_{GS}\text{=}0V$ , $I_{S}\text{=}0.2A$ , $T_{J}\text{=}25^{\circ}\!\mathrm{C}$			1	V

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

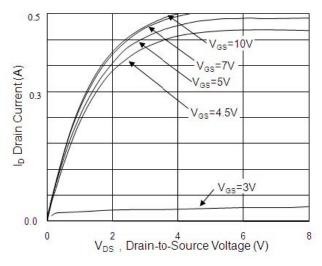
3. The power dissipation is limited by  $150^{\circ}$  junction temperature.

4. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



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## **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

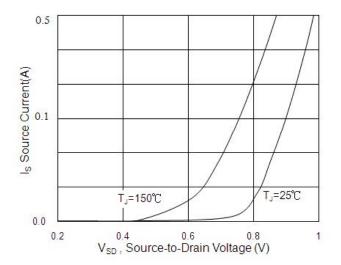
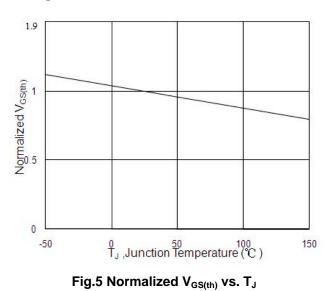


Fig.3 Forward Characteristics of Reverse



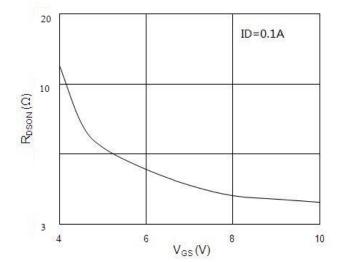


Fig.2 On-Resistance vs. Gate-Source Voltage

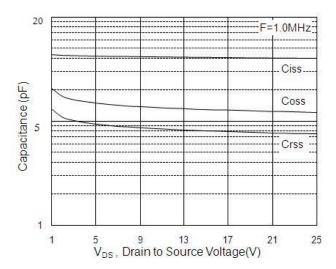


Fig.4 Capacitance

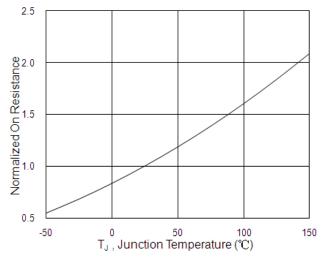
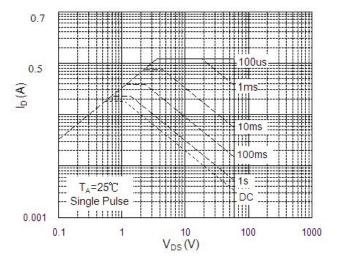


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>

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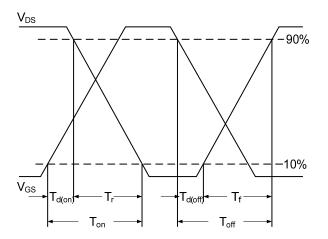


Fig.8 Safe Operating Area

Fig.10 Switching Time Waveform

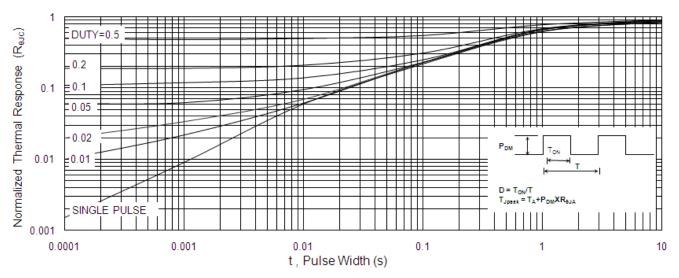


Fig.9 Normalized Maximum Transient Thermal Impedance



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